PROCEEDINGS OF SPIE

Design-Process-Technology Co-optimization for Manufacturability XIII

Jason P. Cain Editor

27–28 February 2019 San Jose, California, United States

Sponsored by SPIE

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Published by SPIE

Volume 10962

Proceedings of SPIE 0277-786X, V. 10962

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Design-Process-Technology Co-optimization for Manufacturability XIII, edited by Jason P. Cain, Proc. of SPIE Vol. 10962, 1096201 · © 2019 SPIE · CCC code: 0277-786X/19/\$18 · doi: 10.1117/12.2533864

Proc. of SPIE Vol. 10962 1096201-1

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Author(s), "Title of Paper," in Design-Process-Technology Co-optimization for Manufacturability XIII, edited by Jason P. Cain, Proceedings of SPIE Vol. 10962 (SPIE, Bellingham, WA, 2019) Seven-digit Article CID Number.

ISSN: 0277-786X ISSN: 1996-756X (electronic)

ISBN: 9781510625716 ISBN: 9781510625723 (electronic)

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